

## Improved thermal stability of poly(ethylene-co-vinyl acetate) as a base material for hot melt adhesives

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The improvement of thermal performance for the hot melt adhesives with polymeric base materials is in progress, due to research that is under way on the preventing discoloring in order to use stably at high temperature for a long time. Recently, hot melt adhesives are necessary to be used in packaging, book-binding, wood-working, and industrial assembling because of their environmental-friendly nature which does not use any solvents; therefore it is very important to improve thermal durability of base materials for this application.

In this study, we developed poly(ethylene-co-vinyl acetate) with specific composition of antioxidants in the high-pressure autoclave reactor on a mass production scale and evaluated its performance on thermal stability.